



Material Content Data Sheet



Sales Product Name		BFP 740F H6327		Issued		24. January 2018		
MA#		MA001289910						
Package		PG-TSFP-4-1		Weight*		1.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.04		371	
	noble metal	gold	7440-57-5	0.003	0.14		1439	
	inorganic material	silicon	7440-21-3	0.023	1.24	1.42	12424	14234
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		395	
	non noble metal	chromium	7440-47-3	0.002	0.12		1183	
	non noble metal	copper	7440-50-8	0.734	39.27	39.44	392737	394394
wire	noble metal	gold	7440-57-5	0.006	0.32	0.32	3221	3221
	encapsulation	organic material	carbon black	0.010	0.51		5138	
encapsulation		plastics	epoxy resin	0.207	11.05		110471	
		inorganic material	silicondioxide	0.745	39.82	51.38	398206	513815
	leadfinish	non noble metal	tin	0.049	2.62	2.62	26180	26180
plating	noble metal	silver	7440-22-4	0.090	4.82	4.82	48156	48156
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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